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PATENT
Atty. Docket: 10191/1466

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#156

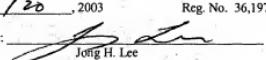
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Applicant : Volker BECKER, *et al.*
Serial No. : 09/581,663
Filed : August 3, 2000
For : METHOD FOR PROCESSING SILICON
BY ETCHING PROCESSES
Group Art Unit : 1746
Examiner : S. AHMED

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
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Signature: 

Jong H. Lee

SUPPLEMENTAL AMENDMENT AFTER FINAL REJECTION
UNDER 37 C.F.R. § 1.116

SIR:

In response to the Final Office Action dated July 5, 2002, please amend the above-identified application, as set forth below. Entry of the amendment is requested since it raises no new issue and merely puts an objected-to claim in condition for allowance.

IN THE CLAIMS:

Please amend claims 53 and 63 as follows:

53. (Amended) A method for etching a silicon layered body, which has a first silicon layer (15) that is provided with an etching mask (10) for defining lateral